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TECHNOLOGY CENTER 2800

To: Commissioner of Patents and Trademarks  
Washington, D.C. 20231

Fr: George O. Saile, Reg. No. 19,572  
20 McIntosh Drive  
Poughkeepsie, N.Y. 12603

Subject:

Serial No. 10/055,094 01/23/02

Il Kwon Shim et al.

HEAT SPREADER ANCHORING & GROUNDING  
METHOD & THERMALLY ENHANCED PBGA  
PACKAGE USING THE SAME

Grp. Art Unit: 2812

#### INFORMATION DISCLOSURE STATEMENT

Enclosed is Form PTO-1449, Information Disclosure Citation  
In An Application.

The following Patents and/or Publications are submitted to  
comply with the duty of disclosure under CFR 1.97-1.99 and  
37 CFR 1.56. Copies of each document is included herewith.

#### CERTIFICATE OF MAILING

I hereby certify that this correspondence is being  
deposited with the United States Postal Service as first class  
mail in an envelope addressed to: Commissioner of Patents and  
Trademarks, Washington, D.C. 20231, on April 1, 2002.

Stephen B. Ackerman, Reg.# 37761

Signature/Date

Saile 4/1/02

U.S. Patent 5,616,957 to Kajihara, "Plastic Package Type Semiconductor Device," discusses a package with an anchored heat spreader.

U.S. Patent 5,977,626 to Wang et al., "Thermally and Electrically Enhanced PBGA Package," reveals a thermally enhanced PBGA and heat spreader design.

U.S. Patent 6,032,355 to Tseng et al., "Method of Forming Thermal Conductive Structure on Printed Circuit Board," discusses a method of manufacturing a thermal conductive structure on a printed circuit board.

U.S. Patent 5,710,459 to Teng et al., "Integrated Circuit Package Provided with Multiple Heat-Conducting Paths for Enhancing Heat Dissipation and Wrapping Around Cap for Improving Integrity and Reliability," discloses a packaged integrated circuit (IC) which includes an IC chip supported and securely attached to an adapter board.

Sincerely,

A handwritten signature in black ink, appearing to read 'SBA', is written over the typed name.

Stephen B. Ackerman,  
Reg. No. 37761

(Use several sheets if necessary)

ST-01-006

10/055, 094

Il Kwon Shim et al.

01/23/02

2812

[illegible]

FOREIGN PATENT DOCUMENTS

[illegible]

OTHER DOCUMENTS (Including Author, Title, Date, Portion or Pages, Etc.)


DATE CONSIDERED

EXAMINER: Initial if citation considered, whether or ~~not~~ citation is in conformance with MPEP § 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to the applicant.